EAST text search notes

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L2 | 337 | 257/773.cor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/25 10:20 |
| L1 | 226 | 257/698.cor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/25 10:07 |
| S1 | 16 | (test or testing or probe) near2 (socket or housing or package or carrier or tray) same (spring) near2 (contact or contacting or electrode or terminal) same (clamp or clamping or lid) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/25 10:05 |
| S32 | 55 | (board or card or socket or carrier or substrate) and (spring or coil or elastic or compressible) near (via or aperture or hole or throughhole or thruhole or opening or viahole) near8 (uncoiled or serpentine or S or leaf) near10 (contact or pad or electrode or terminal or wiring or trace or bga or ball near grid or solder near ball or pin or solder near bump) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 16:05 |
| S31 | 303 | (test or testing or temporary or probe or burn-in) near2 (board or card or socket or carrier or substrate) and (spring or coil or elastic or compressible) near (via or aperture or hole or throughhole or thruhole or opening or viahole) and (spring or coil or elastic or compressible) near2 (contact or pad or electrode or terminal or wiring or trace or bga or ball near grid or solder near ball or pin or solder near bump) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 16:03 |
| S30 | 42 | (test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (spring or coil) near4 (via or aperture or hole or throughhole or thruhole or opening or viahole) near4 (trace or sidewall or plated or plating or lined or wall or edge) near4 (spring or coil) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 14:56 |
| S29 | 382 | (test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (bga or ball near grid or solder near ball or pin or contact or pad or terminal) near3 (spring or coil) near4 (via or aperture or hole or throughhole or thruhole or opening or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 14:47 |
| S28 | 534 | (test or testing or temporary or probe or burn-in) near2 (board or card or socket) and (bga or ball near grid or solder near ball or pin or contact or pad or terminal) near3 (spring) near8 (via or aperture or hole or throughhole or thruhole or opening or viahole) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:42 |
| S27 | 47 | (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (solder near ball or ball near grid) near2 spring | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:38 |
| S4 | 45 | (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (solder near ball or ball near grid) near2 spring | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:28 |
| S26 | 112 | (test or testing or probe or temporary or burn-in) near2 (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (chip or ic or die) near3 (electrode or terminal or contact or solder near ball or ball near grid or bga) near5 (spring) and (clamp or clamping or lid or cover) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:12 |
| S2 | 108 | (test or testing or probe or temporary or burn-in) near2 (socket or housing or package or carrier or tray) near3 (ic or chip or die) and (chip or ic or die) near3 (electrode or terminal or contact or solder near ball or ball near grid or bga) near5 (spring) and (clamp or clamping or lid or cover) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:12 |

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|------|------|---------------------------------------------------------------------------------------------------|----------------------------------------------|----|----|------------------|
| S25 | 97 | 439/77.cor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:00 |
| S24 | 383 | 439/67.cor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 13:00 |
| S23 | 210 | 324/765.cor. and spring | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 11:34 |
| S22 | 1566 | 324/765.cor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 11:16 |
| S21 | 95 | 361/787.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 11:16 |
| S20 | 106 | 361/769.ccls. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 11:03 |
| S19 | 87 | 257/785.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:36 |
| S12 | 87 | 257/785.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:28 |
| S18 | 113 | 257/727.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:19 |
| S11 | 112 | 257/727.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:18 |
| S17 | 42 | 257/710.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:15 |
| S10 | 42 | 257/710.ccor. | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:15 |
| S16 | 13 | "5199879".pn. "6200143".pn. "6374487".pn. "6428328".pn. "6471524".pn. "6512388".pn. "20020016090" | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/10/24 10:09 |

| S15 | 57 | 438/117.ccor. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/24 10:07 |
|-----|-----|----------------|-----|-----|-----|-----|
| S7 | 53 | 438/117.ccor. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/24 10:07 |
| S14 | 269 | 438/15.ccor. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/24 10:04 |
| S6 | 262 | 438/15.ccor. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/24 09:42 |
| S13 | 16 | (test or testing or probe) near2 (socket or housing or package or carrier or tray) same (spring) near2 (contact or contacting or electrode or terminal) same (clamp or clamping or lid) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/10/24 09:41 |

EAST interference Search

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| L5 | 93 | ((chip or die or ic or device) near2 (lead or pad or contact or electrode or terminal or trace) near2 (coil or spring)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:28 |
| L6 | 26 | ((chip or die or ic or device) near2 (lead or pad or contact or electrode or terminal or trace) near5 (coil or spring) and (coil or spring) near2 (opening or aperture or hole or via or viahole or recess or recessed)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:29 |
| L8 | 57 | ((test or temporary or testing or probe or non-permanent) near3 (socket or card or substrate or board or housing or mounting or carrier or package or packaging) and (spring or coil) near (contact or wiring or contacting)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:32 |
| L9 | 0 | ((test or temporary or testing or probe or non-permanent) near3 (socket or card or substrate or board or housing or mounting or carrier or package or packaging) and (spring or coil) near2 (ball near grid or solder near ball or bga)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:32 |
| L10 | 2 | ((coil or coiled) near3 (contact or contacting or trace or pad or terminal or bga or ball near grid or solder near ball or pin or electrode or lead) and (uncoiled or serpentine or leaf or s) near5 (aperture or hole or via or trench or feedthrough or feedthru or viahole or opening)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:34 |
| L14 | 34 | ((uncoiled or serpentine or leaf or s) near3 (spring or elastic) near3 (aperture or hole or via or trench or feedthrough or feedthru or viahole or opening) and (ic or chip or die or device)).clm. | US-PGPUB | OR | ON | 2005/10/25 10:35 |